

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1-4. (Cancelled)

5. (Currently Amended) A wiring board production method comprising:

placing a mask on a substrate of a flexible printed circuit to expose each of a plurality of substrate terminals on the substrate through a corresponding opening in the mask, each opening in the mask being larger than the corresponding substrate terminal;

applying solder through the openings in a the mask to each of the a plurality of substrate terminals; ~~formed on a substrate so as to correspond to a plurality of terminals of an IC package,~~

~~wherein an area of the solder applied to each of the substrate terminals is larger than that of the substrate terminal.~~

mounting an IC package preformed with terminals on the substrate so that the terminals of the IC package are aligned with corresponding substrate terminals through the solder;

melting the solder in a reflow process after mounting the IC package.

6. (Cancelled)

7. (Currently Amended) A wiring board production method according to claim 5, wherein a conductive region is formed between at least one pair of the substrate terminals, and

in the step of applying solder, the solder ~~is applied~~ through a single opening in the mask entirely covers to the substrate so that one of the substrate terminals is entirely covered with the solder and at least partially covers a portion of a width of the conductive region ~~is covered~~ with the solder.

8. (Original) A wiring board production method according to claim 7, wherein the conductive region is a wiring line extending from the substrate terminals.

9. (Original) A wiring board which is produced by the wiring board production method according to claim 5.

10. (Original) An electrooptical apparatus production method including a step of implementing the wiring board production method according to claim 5.

11. (Original) An electrooptical apparatus which is produced by the electrooptical apparatus production method according to claim 10.

12. (Original) An electronic device production method including a step of implementing the electrooptical apparatus production method according to claim 10.

13. (Original) An electronic device which is produced by the electronic device production method according to claim 12.